

**IN THE SPECIFICATION:**

On page 13 of the specification, beginning a line 19, and continuing through page 14, line 2, please amend the paragraph as follows:

Step 706, following the treating of the silicon tile edges in Step 704, chemically etches the silicon tile surfaces. Chemically etching the silicon tile surfaces includes removing silicon material within the range of 50 microns ( $\mu\text{m}$ ) to 500  $\mu\text{m}$ . In some aspects chemically etching the silicon tile surfaces includes immersing the silicon tiles in a solution selected from the group including ~~HMO3~~HNO3/HF/CH<sub>3</sub>COOH (4:1:3) and HF/HNO<sub>3</sub> (1.6:1.8). Alternately, the chemically etching of the silicon tile surfaces in Step 706 includes immersing the silicon tiles in a solution that is a mixture of HNO<sub>3</sub> and HF, with traces of CH<sub>3</sub>COOH.